

MATERIAL DECLARATION SHEET



Material	MF - SMDF
Product Line	Multifuse
Revision Date	April 25, 2005
Revision	A
RoHS Compliant	Yes



No.	Breakdown of part (e.g. Lead, Ceramic body, coating, plating, additive)	Material/substance name (e.g. Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)	
1	Carbon Black	Carbon	0.0014939	1333-86-4	3.84%	11.07%	
2	Copper plating	Copper	0.0028159		7.23%		
3	Foil	Copper	0.0186284	7440-50-8	47.84%	47.84%	
		Nickel	0.0009805	7440-02-0	2.52%	2.52%	
4	PCB Foil	Copper	0.0023674	7440-50-8	6.08%	6.08%	
5	Polymer	Polyethylene Homopolymer	0.0012975	9002-88-4	3.33%	3.38%	
		Proprietary Additives	0.0000175		0.04%		
6	Prepreg	Epoxy	0.0066892		17.18%	28.63%	
		Glass fiber	0.0044589		11.45%		
7	Packing-Carrier Tape	Polystyrene	N/A	9003-53-6			
		Polyethylene Homopolymer	N/A	9002-88-4			
8	Packing-Cover Tape	Polyethylene terephthalate	N/A	25038-59-9			
		Polyethylene Homopolymer	N/A	9002-88-4			
9	Soldering plating	Nickel	0.0001851		0.48%	0.48%	
10	Soldering plating	Gold	0.0000022		0.01%	0.01%	
		Total Weight (%)					
			Total weight (grams)	0.0389365	Total	100%	100%